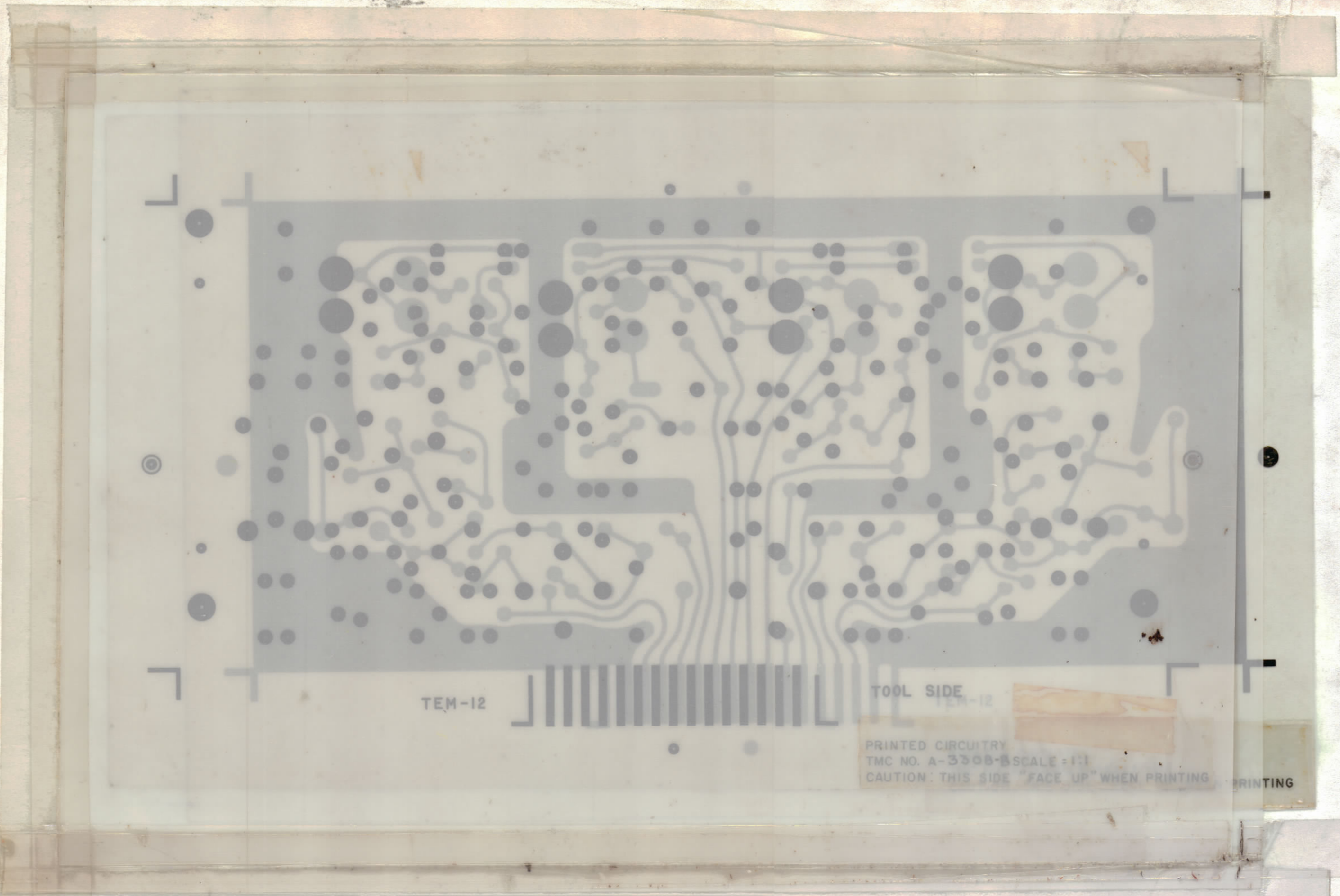


REVISIONS							
ZONE	SYM	DESCRIPTION	DATE	E.M.N. NO.	DRAFT	CHKD	APPD
X1		SEE SHEET 2 OF 2 REVISION "X1"	11-20-63	1	JL		JK
X2		SEE SHEET 2, REVISION "X2"	7/26/64	2	EP		
X3		DELETED "A" HOLES, UPDATED NOTE 5	7-1-64	3	N.P.		JK
X4		ADDED "A" HOLES; REVISED NOTE 5	7/29/64	4	JL		JK
O		ORIGINAL RELEASE FOR PRODUCTION	7-31-64	4	WB		
A		SEE SHEET 2 OF 2 REV. "A"	8-26-64	12181	WB		
B		SEE SHEET 2 OF 2 REV "B"	10-29-64	12786	WB		
C		28 UNMARKED HOLES CHANGED TO "D" HOLES; 12 UNMARKED HOLES CHANGED TO "E" HOLES; HOLE CHART; UNMARKED DIA. WAS .050 REQ. WAS .199; "D" DIA. WAS .166; D & E ADD; SEE SHEET 2 OF 2 REV. "C"	2-11-65	13224	JL		

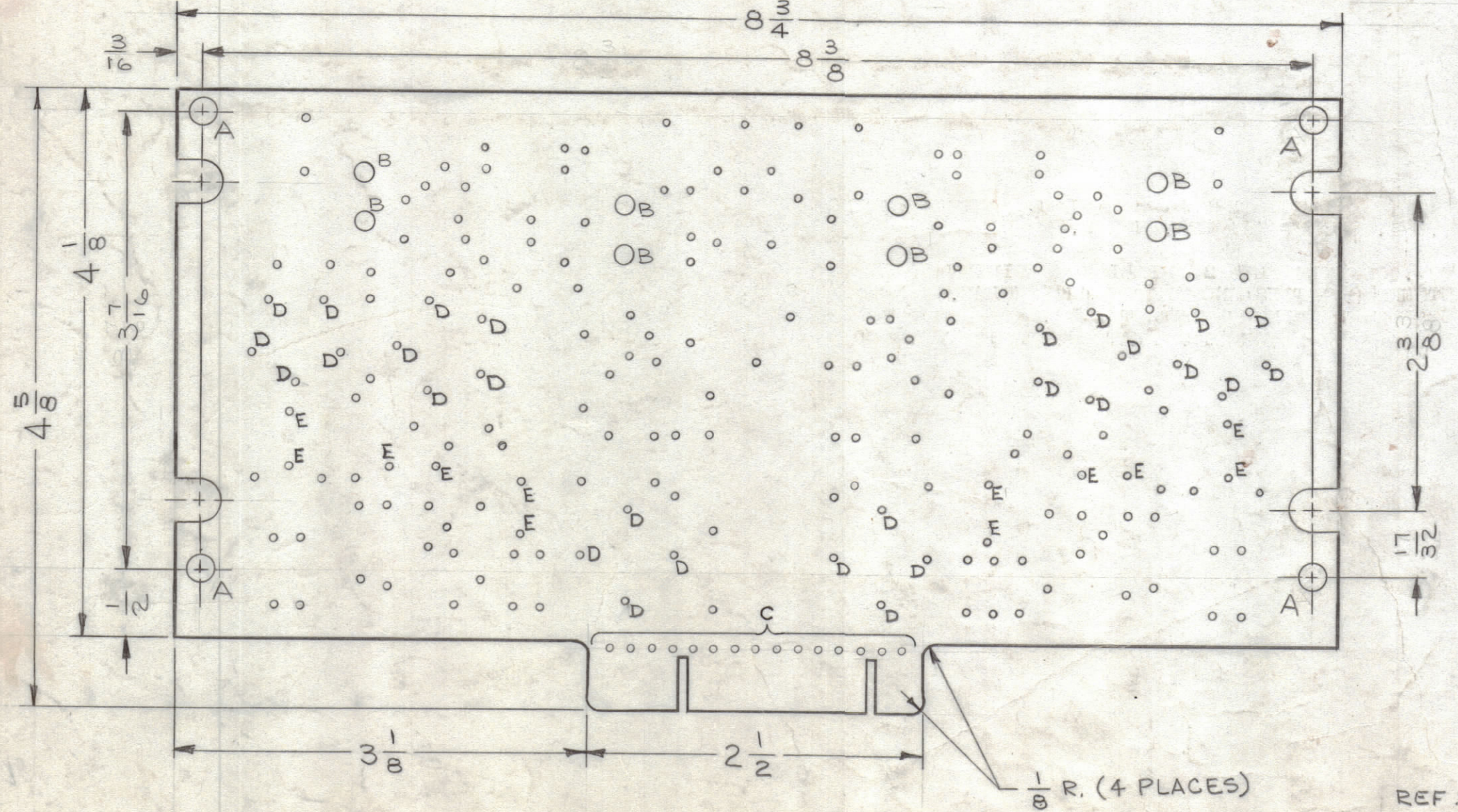
ORIGINAL ARTWORK TO BE REMOVED FROM PROTECTIVE POCKETS WHEN PHOTOGRAPHING. NOTE DOUBLE POCKETS.

HOLE & PAD SPECIFICATIONS			
HOLE	DIA.	PAD DIA.	REQ'D.
UNMARKED	.040	.130	159
A	.161 TO .164	.250	4
B	.166	.310	8
C	.040	CONTACT FINGERS	15
D	.050	.130	28
E	.096	.150	12

- NOTE:
- MATERIAL - G-10 EPOXY GLASS LAMINATE 3/32 THICK, 2 OUNCE COPPER CLAD BOTH SIDES.
 - ALL BOARDS WILL BE DOUBLE-SIDED. WHENEVER A PAD APPEARS ON THE PRINTED CIRCUIT SIDE, A SIMILAR SIZE AND SHAPE SHALL APPEAR ON THE COMPONENT SIDE IN EXACT REGISTER. (EXCEPT WHERE AN EXCEPTION IS NOTED.)
 - FINGER CONTACTS SHALL ALSO APPEAR ON THE COMPONENT SIDE OF BOARD AND SHALL BE CONNECTED WITH A .040 DIA. PLATED-THRU HOLE LOCATED IN THE CENTER OF EACH FINGER CONTACT .050" AWAY FROM THE MAIN BODY OF BOARD.
 - THE PRINTED CIRCUIT BOARDS SHALL BE KEYED WITH SLOTS .070" WIDE & .400" HIGH LOCATED BETWEEN FINGER CONTACTS 4 & 5, 13 & 14 AS VIEWED FROM COMPONENT SIDE OF BOARD.
 - (A) ALL HOLES ARE TO BE PLATED-THRU WITH MINIMUM COPPER PLATING THICKNESS OF .001, EXCEPT "A" MTG. HOLES.
(B) PLATE .0003 TO .0005 NICKEL & 25 MILLIONTHS MINIMUM OF GOLD ALL ETCHED SURFACES AND PLATED-THRU HOLES.



ETCHING, PRINTED CIRCUIT (A-3308-1)



REF: CK 701

MACHINING (A-3308-2)
DO NOT SCALE, WORK TO DIMENSIONS

NOTES

QTY./UNIT	LFSA-1	AX-470
SCALE	MODEL USED ON	ASS'Y. NO.
1:1	A	

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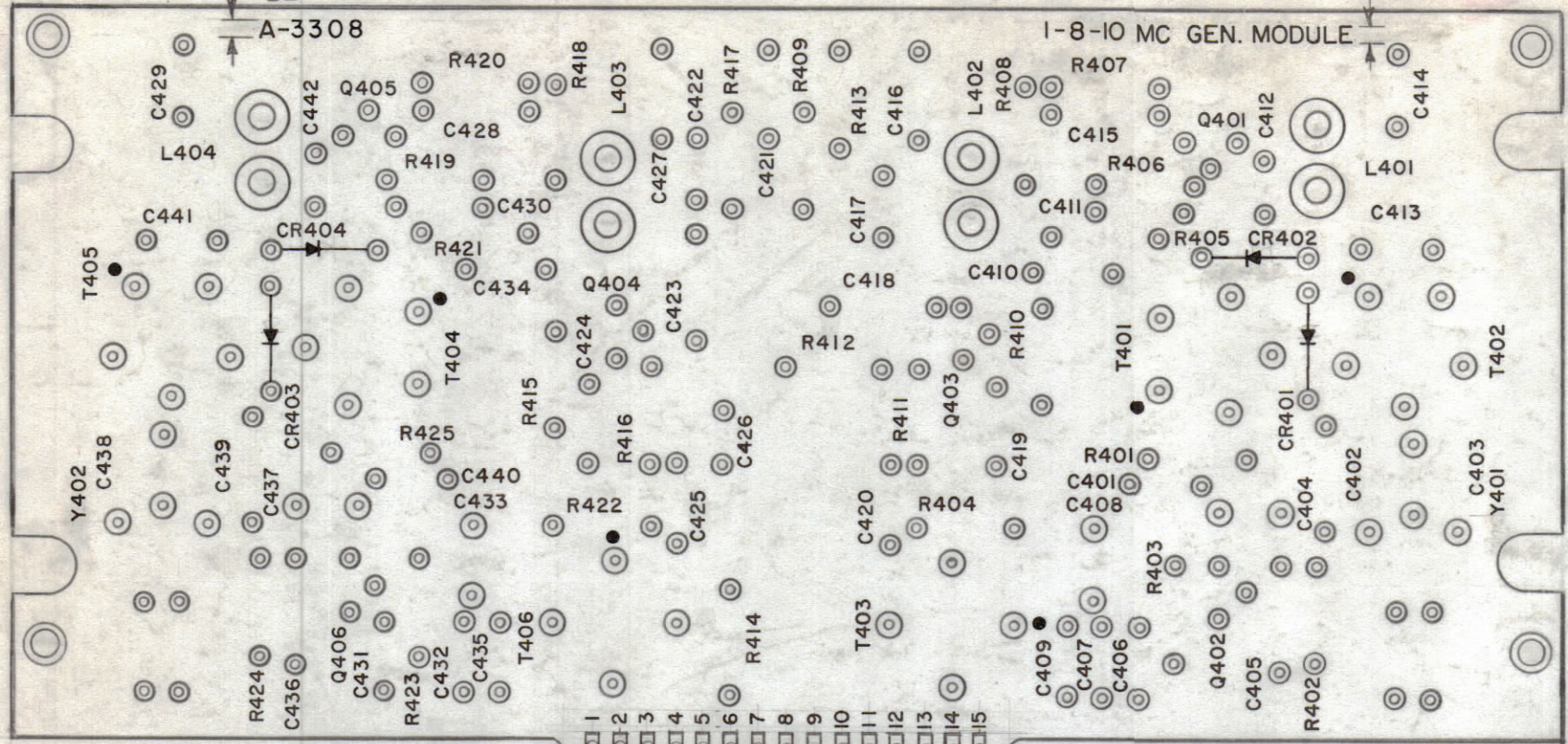
THE ORIGINAL ARTWORK TO BE SUPPLIED BY TMC FOR PHOTOGRAPHING. (SCALE 1:1)

REQ'D.	ITEM	PART NUMBER	DESCRIPTION	SYMBOL
M. GELLMAN LIST OF MATERIAL				
MATERIAL		THE TECHNICAL MATERIEL CORP. MAMARONECK, NEW YORK		
SEE NOTE #1		TITLE PRINTED CIRCUIT BOARD, ASS'Y. (1-8-10 MC GEN. MODULE)		
FINISH		SEE NOTE #1		
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES AND INCLUDE CHEMICALLY APPLIED OR PLATED FINISHES	DRAWN	DATE	FINAL APPROVAL	
	Checked	4-19-63	RJC	
		7/2/64		
DECIMALS .X ± .05 TOLERANCES .XX ± .01 .XXX ± .005	FRACTIONS ± 1/64 ANGLES ± 0° 30'	ELECT. DES.	DATE	DATE
		WB	7/2/64	
		MECH. DES.	DATE	DATE
			A 3308	C
			SHEET 1 OF 2	REV. LTR.

A 3308

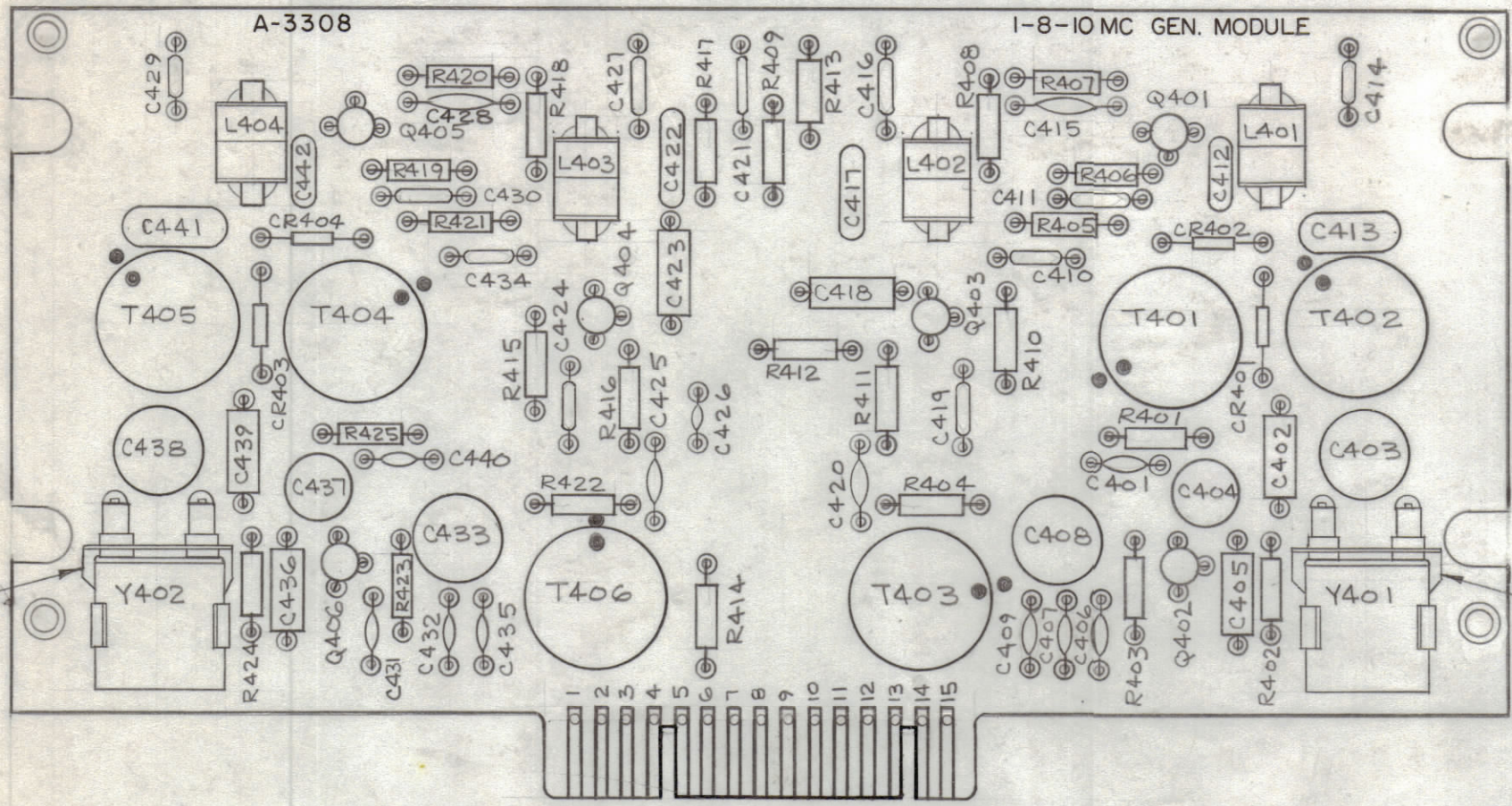
-UNLESS OTHERWISE SPECIFIED-

- 1-ALL LETTERING TO BE 5/64 HIGH BLACK GOTHIC, LOCATE AS SHOWN ± 1/64.
- 2-MARKING PROCESS: AS PER TMC SPEC S-727.
- 3-ALL DOTS TO BE 1/64 DIA, .010 STROKE.



NOTE:
MARK TMC P/N WITH
LATEST REVISION LETTER

MARKING LAYOUT (A-3308-3)



ELECTRICAL ASS'Y (A-3308-5)

Q401 THRU Q406
CR401 THRU CR404
C403, 408, 433, 438

L401 THRU L404

C410, 411, 414, 416, 419, 421, 424, 427, 429, 430, 434
C401, 406, 407, 409, 420, 425, 431, 432, 435, 440

R403, 405, 410, 415, 419, 421, 423

R402, 404, 406, 407, 408, 411, 416, 418, 422, 424, 424

REF: CK-701

LETTERING ON THIS SIDE

29
MOUNT IN ALL "A" HOLES

SUB-ASS'Y (A-3308-4)

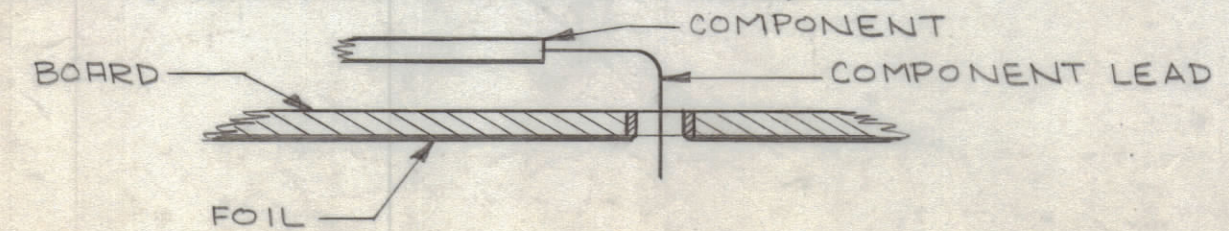
		REVISIONS					
ZONE	SYM	DESCRIPTION	DATE	E.M.N. NO.	DRAFT	CHKD	APPD
#	X1	REVISED PT N°s & DESCRIPTION OF ITEMS 26 THRU 28.	1/29/63	1	J.L.		JL
#	X2	ITEMS (19) THRU (23) ADDED	7/24/64	2	SP		SP
EP, 63	X3	ITEM 29, NT144-0440 & SUB ASSY (A3308-4) DELETED	7-1-64	3	NP	@	NP
DB, AT	X3	ITEMS 20 & 21 ADDED; FUNGUS NOTE ADDED					
	X4	ADDED ITEM 29, SUB ASSY, MTG HOLES & SLOTS.	7/29/64	4	JL	@	JL
	O	ORIGINAL RELEASE FOR PRODUCTION	7-31-64		LB		LB
	A	TO IT. 11, 13, 14 P/N "J" ADD. TO IT. 15, 17 P/N H55 & IT. 18 H35 ADD.	8-26-64	12181	LB		LB
	B	IT. 10 WAS C412 R474, IT. 17 WAS CM112E152H55 IT. 18 WAS CM112E622H35, IT. 20 WAS CR113A/U, IT. 21 W. CR113M	10-29-64	12786	LB		LB
#	C	IT. (28) WAS ZNIG37; IT. (24) WAS IN100 (SEE SHEET #1)	2-10-65	13224	Elmer		Elmer

35			
34			
33			
32			
X 31	B5 100	SOLDER, SOFT	
2 30	TS 167-1	SOCKET, CRYSTAL	XY401 XY402
4 29	NT-144-0440	NUT, PLAIN, SPLINE	
2 28	TZ 169	TRANSFORMER, R.F., FIXED	T403, 406
2 27	TZ 171	TRANSFORMER, R.F., FIXED	T402, 405
2 26	TZ 164	TRANSFORMER, R.F., FIXED	T401, 404
6 25	TX105	TRANSISTOR	
4 24	IN100	DIODE	
4 23	CV-109-8	CAPACITOR, VARIABLE	
2 22	CV 112-4	CAPACITOR, VARIABLE	C404, 437
1 21	CR113-15	CRYSTAL (10 MC)	Y402
1 20	CR113-14	CRYSTAL (8 MC)	Y401
4 19	CL 327	COIL, RF	
2 18	CM112E622J3S	CAPACITOR, FIXED, MICA	C413, 441
2 17	CM112E152D5S	CAPACITOR, FIXED, MICA	C417, 422
2 16	CM111E471H5S	CAPACITOR, FIXED, MICA	C412, 418
1 15	CM111E321H5S	CAPACITOR, FIXED, MICA	C442
2 14	CM15B470J	CAPACITOR, FIXED, MICA	C405, 436
1 13	CM15B331J	CAPACITOR, FIXED, MICA	C423
1 12	CM15B240J	CAPACITOR, FIXED, MICA	C439
1 11	CM15B101J	CAPACITOR, FIXED, MICA	C402
11 10	CC-112R474M	CAPACITOR, FIXED, CERAMIC	C421
10 9	CC-100-35	CAPACITOR, FIXED, CERAMIC DISC.	
3 8	CC-100-29	CAPACITOR, FIXED, CERAMIC DISC.	C415, 426, 428
1 7	RC20GF822K	RESISTOR, FIXED COMPOSITION	R409
1 6	RC20GF392K		R417
2 5	RC20GF332K		R412, 414
1 4	RC20GF331K		R413
7 3	RC20GF103K		
11 2	RC20GF102K		
2 1	RC20GF101K	RESISTOR, FIXED COMPOSITION	R401, 425

REQ'D.	ITEM	PART NUMBER	DESCRIPTION	SYMBOL
M. GELLMAN LIST OF MATERIAL				
MATERIAL		THE TECHNICAL MATERIEL CORP. MAMARONECK, NEW YORK		
FINISH		TITLE PRINTED CIRCUIT BOARD, ASS'Y. (1-8-10 MC GEN. MODULE)		
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES AND INCLUDE CHEMICALLY APPLIED OR PLATED FINISHES				
DRAWN G. Swan		DATE 7-3-63		FINAL APPROVAL KRC
CHECKED @		DATE 7-26-64		DATE 7-26-64
ELECT. DES. W. J.		DATE 7-26-64		DATE 7-26-64
MECH. DES.		DATE		DATE
DECIMALS X ± .05 XX ± .01 XXX ± .005		FRACTIONS ± 1/64 ANGLES ± 0° 30'		TOLERANCES
SHEET 2 OF 2				
REV. LTR.				

ASSEMBLY NOTICE

- 1- TO MOUNT COMPONENTS INSERT LEAD THROUGH PLATED-THRU HOLES AND BEND ABOUT 1/16 OF LEAD OVER COPPER FOIL AS SHOWN.
- 2- APPLY HEAT AND SOLDER TO LEAD AND FOIL - CAUTION- TOO MUCH HEAT WILL CAUSE THE FOIL TO SEPARATE FROM THE BOARD.
- 3- CLEAN AND INSPECT AS PER S-676.
- 4- FUNGUS PROOF PER TMC SPEC S113.



NOTES

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Q'TY./UNIT	LFSA-1	AX-470
SCALE 1:1	MODEL USED ON A	ASS'Y. NO.